NVGS5120P

Product Preview

Power MOSFET

−60 V, −3.0 A, Single P−Channel, TSOP−6

ON Semiconductor®

http://onsemi.com

$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	I_D MAX
−60 V	111 mΩ @ −10 V	−3.0 A
	142 mΩ @ −4.5 V	

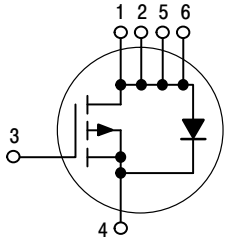
Features

- 60 V BVds, Low $R_{DS(on)}$ in TSOP−6 Package
- 4.5 V Gate Rating
- AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR−Free and are RoHS Compliant

Applications

- High Side Load Switch
- Power Switch for Printers, Communication Equipment

P−Channel



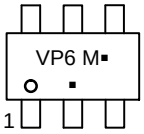
MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain−to−Source Voltage			V_{DSS}	−60	V
Gate−to−Source Voltage			V_{GS}	±20	V
Continuous Drain Current (Note 1)	Steady State	T_A = 25°C	I_D	−2.6	A
		T_A = 85°C		−2.1	
	t ≤ 5 s	T_A = 25°C		−3.0	
Power Dissipation (Note 1)	Steady State	T_A = 25°C	P_D	1.5	W
	t ≤ 5 s			1.9	
Continuous Drain Current (Note 2)	Steady State	T_A = 25°C	I_D	−1.9	A
		T_A = 85°C		−1.5	
Power Dissipation (Note 2)		T_A = 25°C	P_D	0.8	W
Pulsed Drain Current	t_p = 10 μs		I_{DM}	−11	A
Operating Junction and Storage Temperature			T_J, T_{STG}	−55 to 175	°C
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

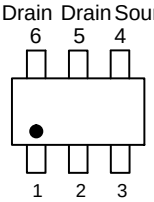
MARKING DIAGRAM

TSOP−6
CASE 318G
STYLE 1



VP6 = Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

PIN ASSIGNMENT



THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction−to−Ambient – Steady State (Note 1)	$R_{\theta JA}$	102	°C/W
Junction−to−Ambient – t = 5 s (Note 1)	$R_{\theta JA}$	77.6	
Junction−to−Ambient – Steady State (Note 2)	$R_{\theta JA}$	200	

1. Surface−mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)
2. Surface−mounted on FR4 board using the minimum recommended pad size.

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

ORDERING INFORMATION

Device	Package	Shipping†
NVGS5120PT1G	TSOP−6 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain−to−Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = −250 μA		−60			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = −48 V	T_J = 25°C			−1.0	μA
			T_J = 125°C			−5.0	
Gate−to−Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±12 V				±100	nA
		V_{DS} = 0 V, V_{GS} = ±20 V				±200	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = −250 μA		−1.0		−3.0	V
Drain−to−Source On Resistance	$R_{DS(on)}$	V_{GS} = −10 V, I_D = −2.9 A			72	111	mΩ
		V_{GS} = −4.5 V, I_D = −2.5 A			88	142	
Forward Transconductance	g_{FS}	V_{DS} = −5.0 V, I_D = −6.0 A			10.1		S
CHARGES, CAPACITANCES AND GATE RESISTANCE							
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = −30 V			942		pF
Output Capacitance	C_{OSS}				72		
Reverse Transfer Capacitance	C_{RSS}				48		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = −10 V, V_{DS} = −30 V; I_D = −2.9 A			18.1		nC
Threshold Gate Charge	$Q_{G(TH)}$				1.2		
Gate−to−Source Charge	Q_{GS}				2.7		
Gate−to−Drain Charge	Q_{GD}				3.6		
SWITCHING CHARACTERISTICS (Note 4)							
Turn−On Delay Time	$t_{d(ON)}$	V_{GS} = −10 V, V_{DS} = −30 V, I_D = −1.0 A, R_G = 6.0 Ω			8.7		ns
Rise Time	t_r				4.9		
Turn−Off Delay Time	$t_{d(OFF)}$				38		
Fall Time	t_f				12.8		
DRAIN−SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	V_{GS} = 0 V, I_S = −0.9 A	T_J = 25°C		−0.75	−1.0	V
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, d_{IS}/d_t = 100 A/μs, I_S = −0.9 A			18.3		ns
Charge Time	t_a				15.5		ns
Reverse Recovery Charge	Q_{RR}				15.1		nC

3. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%
4. Switching characteristics are independent of operating junction temperatures

TYPICAL CHARACTERISTICS

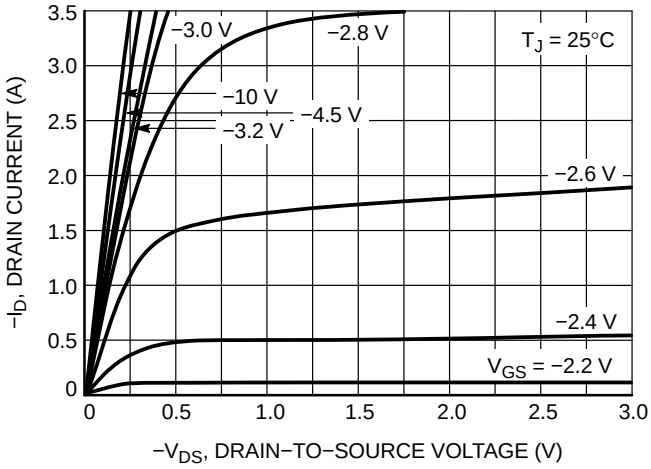


Figure 1. On−Region Characteristics

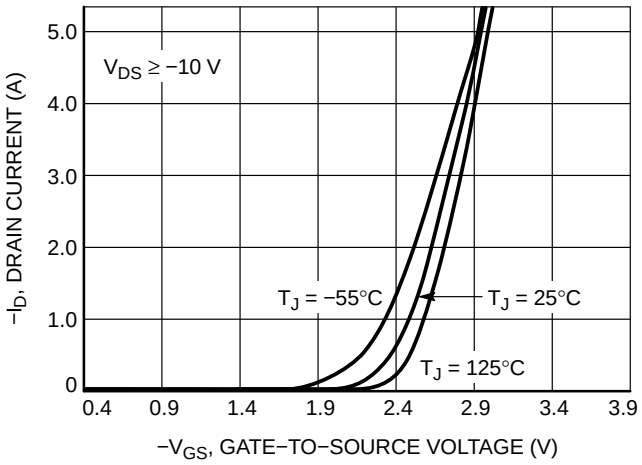


Figure 2. Transfer Characteristics

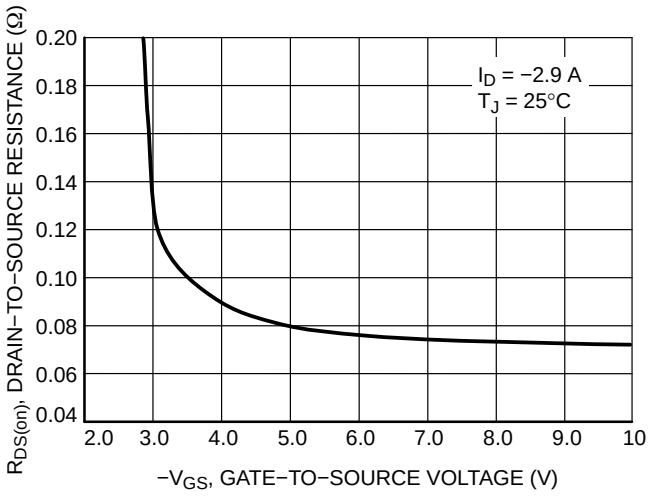


Figure 3. On−Resistance vs. Gate Voltage

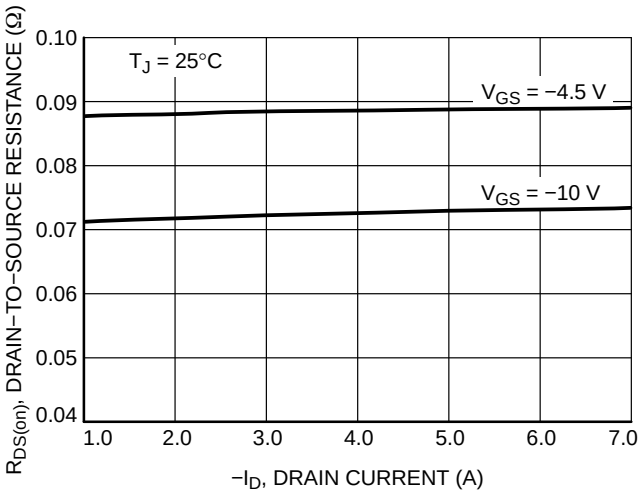


Figure 4. On−Resistance vs. Drain Current and Gate Voltage

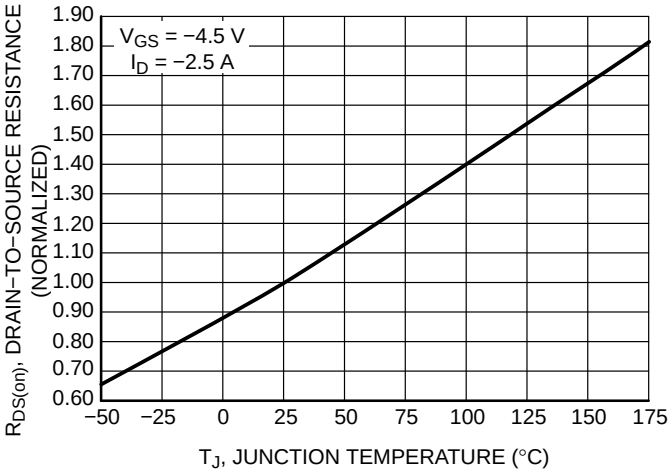


Figure 5. On−Resistance Variation with Temperature

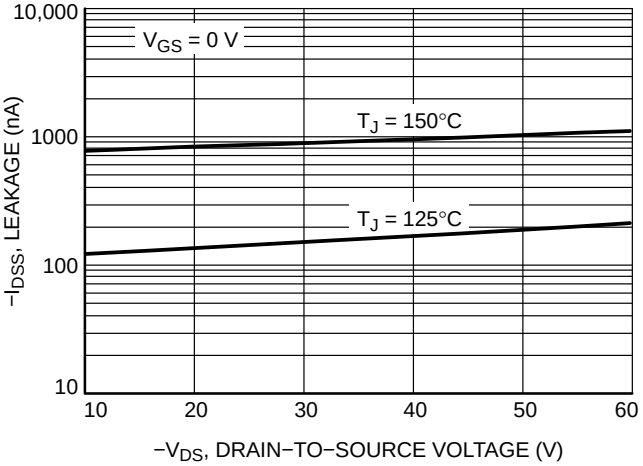


Figure 6. Drain−to−Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

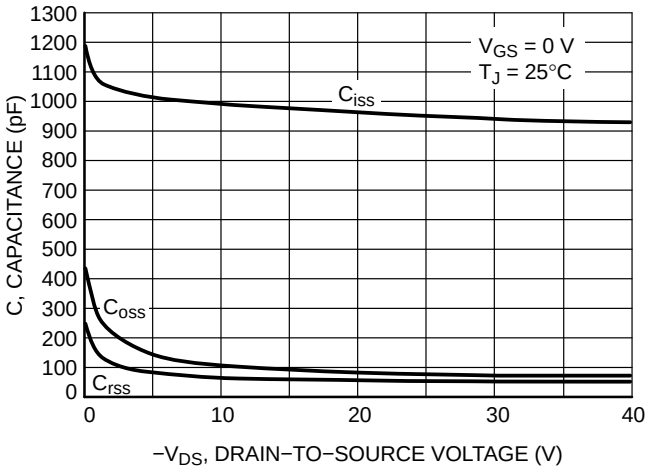


Figure 7. Capacitance Variation

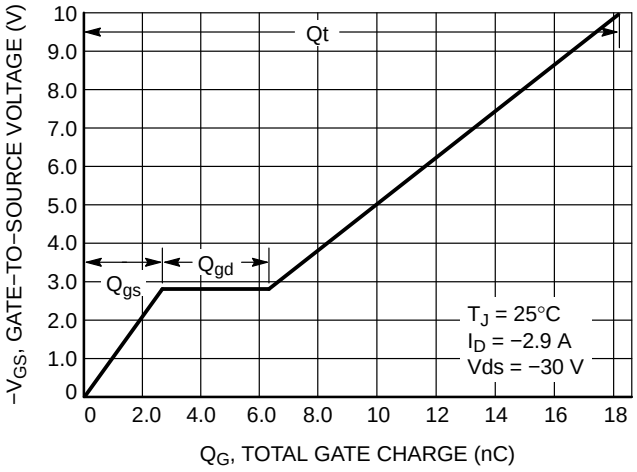


Figure 8. Gate−to−Source Voltage vs. Total Charge

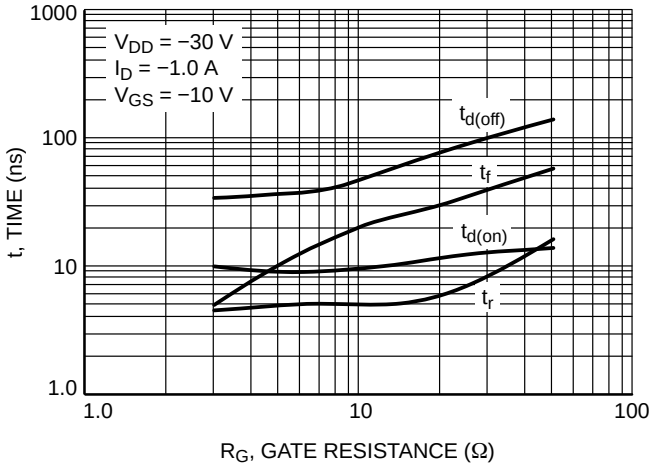


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

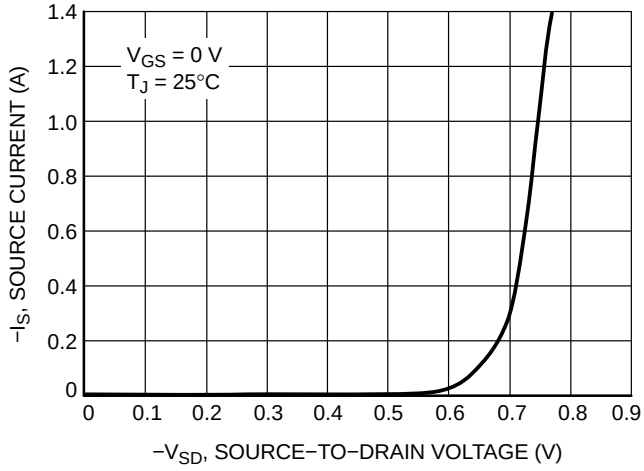
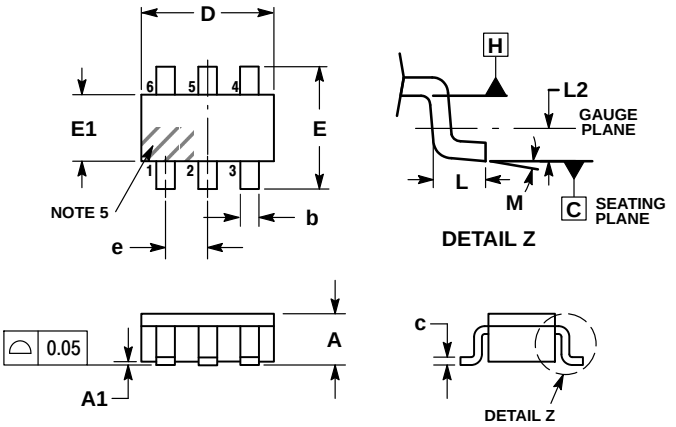


Figure 10. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

TSOP−6
CASE 318G−02
ISSUE V

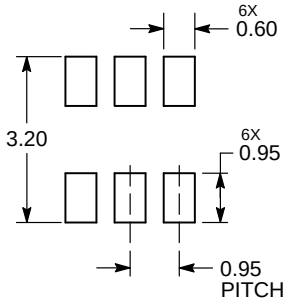


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.90	3.00	3.10
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.85	0.95	1.05
L	0.20	0.40	0.60
L2	0.25 BSC		
M	0°	–	10°

STYLE 1:
PIN 1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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